

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE BY SECURED PARTY
CONVEYING PARTY DATA	
Name	Execution Date
MORGAN STANLEY SENIOR FUNDING, INC.	02/06/2013
RECEIVING PARTY DATA	
Name:	NATIONAL HYBRID, INC.
Street Address:	3285 Veteran's Memorial Hwy, Suite A-7
City:	Ronkonkoma
State/Country:	NEW YORK
Postal Code:	11779
PROPERTY NUMBERS Total: 6	
Property Type	Number
Patent Number:	6388264
Patent Number:	6613605
Patent Number:	7132356
Patent Number:	7271028
Patent Number:	7421353
Application Number:	11400970
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	058438-14-0407

CH \$240.00 6388264

NAME OF SUBMITTER:

Catherine R. Howell, Senior Paralegal

Total Attachments: 4

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**RELEASE OF SECURITY INTEREST
IN UNITED STATES PATENTS**

This release of security interest in United States patents (this "Release"), effective as of February 6, 2013, is granted by MORGAN STANLEY SENIOR FUNDING, INC., with principal offices at 1 Pierrepont Plaza, Brooklyn, NY 11201 (the "Grantee"), in its capacity as Collateral Agent (as such term is defined in that certain U.S. Guaranty and Collateral Agreement, dated as of June 1, 2011, by and among API TECHNOLOGIES CORP., and other grantors from time to time party thereto and the Grantee, as amended, modified, restated, supplemented or otherwise modified from time to time, the "U.S. Guaranty and Collateral Agreement") for the Secured Creditors (as defined in the U.S. Guaranty and Collateral Agreement) to NATIONAL HYBRID, INC., a New York corporation (the "Grantor") with principal offices at 3285 Veteran's Memorial Hwy, Suite A-7, A-10, Ronkonkoma, NY 11779, as follows:

W I T N E S S E T H:

WHEREAS, the Grantor has heretofore granted to the Grantee a security interest in (i) all of the Grantor's right, title and interest in, to and under the United States patents set forth on Schedule A attached hereto ("Patents"); (ii) all proceeds and products of the Patents; and (iii) all causes of action arising prior to or after June 1, 2011 for infringement of any of the Patents (collectively, the "Patent Collateral") to secure the satisfactory performance and payment of all the Obligations (as defined in the U.S. Guaranty and Collateral Agreement), which security interest was recorded on June 9, 2011, at Patent Reel 026418, Frame 0488 in the United States Patent and Trademark Office ("USPTO"); and


WHEREAS, the Grantee wishes to release and restore all right, title and interest in and to the Patent Collateral to the Grantor and to dissolve any and all liens and encumbrances respecting the Patent Collateral under the U.S. Guaranty and Collateral Agreement and that certain Grant of Security Interest in United States Patents, dated June 1, 2011, between Grantor and Grantee.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, the Grantee hereby, without recourse and without representation or warranty of any kind (either express or implied), releases, discharges, quit claims, and relinquishes unto the Grantor any and all right, title, and interest in and to the Patent Collateral.

-SIGNATURE PAGE FOLLOWS-

IN WITNESS WHEREOF, the undersigned has caused this Release to be duly executed as of the date first written above.

MORGAN STANLEY SENIOR FUNDING, INC.,
as Grantee

By 
Name: STEPHEN B. KIL
Title: VP

SCHEDULE A

Patent	Patent No. / Appl. No.	Issue Date
OPTOCOUPLER PACKAGE BEING HERMETICALLY SEALED	6,388,264	5-14-2002
INTERCONNECTION METHOD ENTAILING PROTUBERANCES FORMED BY MELTING METAL OVER CONTACT AREAS	6,613,605	9-2-2003
INTERCONNECTION METHOD	7,132,356	11-7-2006
HIGH DENSITY ELECTRONIC INTERCONNECTION	7,271,028	9-18-2007
DIGITAL INTEGRATION METHOD	7,421,353	9-2-2008
HIGH DENSITY ELECTRONIC INTERCONNECTION	11/400,970	4-10-2006